Solderite Flux WPF-19

Introduction：

Various protective methods are used for the protection of copper foil of printed circuit boards. It is predicted, however, that the use of lead contained in the organic solvent of resin-based pre-flux and in solder leveler will strictly controlled in future from the need of dealing with environmental problems. Under the situations as stated above, a large expectation is placed on water-soluble, heat resistant pre-flux.

Outstanding Features：

- Organic film coat excellent in heat and humidity resistance is formed on the surface of copper.
- Heat resistance is improved as compared with the conventional water-soluble pre-flux. Excellent solderability is shown even after reflow processing of plural number of times.
- Excellent in the spread of wettability of solder paste.
- Excellent in the flow solderability of lead-free solder.
- Film coat will be formed in a processing time from 60 to 90 seconds.
- Thin and uniform film is formed to produce excellent smoothness in copper foil land, so that the material is suited for high density packaging boards.
- No flammability as no organic solvent is contained.

Specifications：

Appearance	：Blue transparent liquid
Specific gravity	：1.07±0.01（20℃）
PH	：3.5~3.7（when used on the line, 20℃）
	：2.9~3.1（on delivery, 20℃）
Acid value	：260±20
Concentration of effective ingredient	：100±10％